

Title (en)  
RHEOLOGY-CONTROLLED EPOXY-BASED COMPOSITIONS

Title (de)  
RHEOLOGISCH KONTROLLIERTE AUF EPOXYID BASIERENDE ZUSAMMENSETZUNGEN

Title (fr)  
COMPOSITIONS A BASE DE RESINE EPOXYDE REGULEES PAR AGENT RHEOLOGIQUE

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Application  
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Abstract (en)  
[origin: WO0183607A1] This invention relates to rheology-controlled epoxy-based compositions, particularly well suited for use in coating applications such as in the assembly of ink jet printheads for the printing industry, and in the microelectronics industry such as in the assembly of semiconductor devices.

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**C08K 5/54**; **H01L 51/40**; **C08L 63/00**; **H01L 23/00**; **H01L 21/00**; **C09J 163/00**

IPC 8 full level  
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Citation (search report)  
• [X] DE 19918580 A1 19991028 - NITTO DENKO CORP [JP]  
• [X] US 3532653 A 19701006 - SMEAL THOMAS W  
• [X] US 5644003 A 19970701 - ARAI NORIYUKI [JP], et al  
• [X] US 5013383 A 19910507 - CHAPMAN CHARLES B [US]  
• [X] US 5346743 A 19940913 - UCHIDA KEN [JP], et al  
• [X] US 4248920 A 19810203 - YOSHIZUMI AKIRA, et al  
• [X] EP 0733689 A1 19960925 - KONISHI CO LTD [JP]  
• [X] US 5476884 A 19951219 - KAYABA KEIJI [JP], et al  
• [XP] WO 0056799 A1 20000928 - LOCTITE CORP [US], et al  
• [X] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 03 31 March 1997 (1997-03-31)  
• See references of WO 0183607A1

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